Scholarship Application Materials

You may be eligible to receive a full-tuition scholarship next year!!!

Follow five simple steps to be considered for one of over 10 undergraduate scholarships awarded by the ASM Materials Education Foundation every year! Our scholarship form, eligibility requirements and application procedures are enclosed; the form can be reproduced locally.  Apply by May 1 to see if you qualify!  If you have any questions regarding this scholarship program contact:

ASM Materials Education Foundation
Undergraduate Scholarship Program
Materials Park, Ohio 44073-0002
Tel: 440 • 338 • 5151    Fax: 440 • 338 • 4634   E-Mail: jeane.deatherage@asminternational.org

George A. Roberts Scholarships (Up to 7) $6,000 each: Established in 1995 through a generous contribution by Dr. George A. Roberts, Past President of ASM and Retired CEO of Teledyne, to the ASM Foundation as an expression of his commitment to education and the materials science and engineering community.

William P. Woodside Founder’s Scholarship (1) Tuition up to $10,000: Established in 1996 by Mrs. Sue Woodside Shulec in honor of her grandfather William Park Woodside, a man whose vision and leadership evolved into the founding of ASM International.

Lucille & Charles A. Wert Scholarship – (1) Tuition up to $10,000: Established in 2006 through a generous bequest by Dr. & Mrs. Charles Wert as an expression of their commitment to education and the materials science and engineering community.

William & Mary Dyrkacz Scholarships – Four scholarships of $6,000 (each). Established in 2011 through a generous contribution by Mr. & Mrs. William Dyrkacz as an expression of their commitment to education and the materials science and engineering community.

Ladish Co. Foundation Scholarships - Two scholarships of $2,500 (each). (Student must be a Wisconsin resident and must attend a Wisconsin university to qualify.)

ASM Outstanding Scholars Awards* (3) $2,000 each, to recognize distinguished scholars.

Edward J. Dulis Scholarship (1) $1,500: Established in 2003 by the family of Edward J. Dulis, a Fellow of ASM International. This scholarship is awarded to an undergraduate student in materials science and engineering based on academic merit.

John M. Haniak Scholarship (1) $1,500: Established in 2003 by the family of John Myron Haniak, who was a life member of ASM International. This scholarship is awarded to an undergraduate student in materials science and engineering based on academic merit and financial need. (Student must be a Pennsylvania resident and / or must attend a Pennsylvania university to qualify.)

David J. Chellman Scholarship (1) $2,500: Established in 2014 by Mrs. Arline Denny in honor of her husband David James Chellman, who was a long-standing Senior Technical Fellow with Lockheed Martin Corporation, a life member of ASM International, and who enthusiastically served on the AeroMat Conference Organizing Committee for more than 25 years. This scholarship is an expression of his commitment to education and the materials science and engineering community, and is awarded based on academic merit and financial need.

The ASM Materials Education Foundation undergraduate scholarship program is generously supported by member contributions and other gifts. In addition to the ASM Foundation Scholarship Program, many ASM Professional Chapters offer scholarships. Contact the ASM Materials Education Foundation for the name of the local ASM chapter scholarship contact.

*These scholarships are open to international student members, and are merit-based. All others are open to Material Advantage students in North America only and are both merit and need-based.
WHO MAKES THE DECISIONS?

The Undergraduate Scholarship Program is administered by the ASM Action in Education Team. The following rules govern application for and granting of all scholarships.

AM I ELIGIBLE?

To be eligible for all awards you must meet ALL of the following general eligibility requirements:

♦ Must be a Material Advantage student member.
♦ Must have an intended or declared major in metallurgy or materials science engineering. Applicants majoring in related science or engineering disciplines will be considered if they demonstrate a strong academic emphasis and interest in materials science.
♦ Must have completed at least 1 year of college to apply for all awards.
♦ Must have junior or senior standing in the fall at a North American University to be eligible for the Roberts, Woodside, Wert, Dulis and Haniak scholarships need-based awards. University must have an accredited science and engineering program leading to a bachelor degree.

HOW DO I APPLY?

In order to be considered, you must follow these five steps and submit an application package by 1 May:

Step 1: Complete and sign Part 1 of the Application Form.

Step 2: Write a personal statement (two pages maximum). A resume may be included.

Step 3: Submit a current academic transcript through the Fall term. An official student copy is acceptable.

Step 4: Attach no more than two completed Undergraduate Scholarship Recommendation Forms with at least one from a professor in applicant’s major department.

Step 5: Include a photograph for publication (not to be sent to Selection Committee.)

If you are attending a North American University and wish to be considered for the Roberts, Woodside, Wert, Dulis and Haniak need-based scholarships you must also:

Step 6: Complete Part 2 of the Application Form, including a personal statement and a financial aid officer contact. NOTE: You need to complete this section to be considered for most of the ASM Foundation scholarships!

HOW ARE DECISIONS MADE?

ASM Undergraduate scholarships are intended to encourage and support capable students with interest and potential in the field of metallurgy/materials engineering and related careers. Information is drawn from your application, transcript, personal statement and recommendations. The Selection Committee considers a variety of factors including:

Academic Achievement : Grades, Courses selected, Interdisciplinary skills / interests

Interest in the Field : Knowledge of metallurgy/materials engineering field, Demonstrated interest through activities/jobs, Potential for related career

Personal Qualities : Motivation, Social Values, Maturity, Goals

♦ The Roberts, Woodside, Wert, Dulis and Haniak scholarships are only awarded to students studying in North America who demonstrate financial need in addition to academic merit.
♦ ASM Outstanding Scholar awards are open to international students. These are merit awards and financial need is not considered.

WHAT ELSE SHOULD I KNOW?

1. Each award is for one year; students must re-apply for consideration the following year. No applicant may receive more than two consecutive scholarship awards.
2. Any number of students from an institution may apply.
3. Colleges and universities are urged not to reduce other support to students who receive ASM Scholarships.
4. Applicants will be considered for all awards for which they qualify.
5. All application materials should be submitted together by the applicant.
6. The application and materials must be sent by 1 May.
7. All applicants will be contacted following the committee review. Award winners will be notified by mail by 31 July.

WHERE CAN I GET AN APPLICATION?

Official application forms are available online at www.asmfoundation.org, or may be obtained from:

ASM MATERIALS EDUCATION FOUNDATION
Scholarship Program
Materials Park, Ohio 44073-0002
Phone: (800) 336-5152 / (440) 338-5151
Fax: (440) 338-4634
E-mail: jeane.deatherage@asminternational.org
ASM MATERIALS EDUCATION FOUNDATION SCHOLARSHIP APPLICATION

PART 1 Fill out completely. Please TYPE or PRINT clearly in BLACK INK. All materials must be submitted in English.

1. □ Miss □ Mrs. □ Ms. □ Mr. Full Name: ____________________________________________

2. Indicate preferred address for contact and mailing:

   Preferred Address (May-August) Preferred Address (September-December)

   Address: ________________________________ Address: ________________________________

   City/State: ___________________________ City/State: ___________________________


   Telephone: ___________________________ Telephone: ___________________________

   E-mail(1): ___________________________ E-mail(2): ___________________________

   (Must provide personal email, other than your school email.)

3. Material Advantage Student Member Number: ____________________________ Join Date (Mo/Yr): ____________________________

   (Student membership is required for scholarship consideration.)

4. Country of citizenship: __________________________________________

5. College or University: __________________________

6. Fall Class Standing: □ 2nd yr □ 3rd yr □ 4th yr Expected graduation date (Mo/Yr): _______ Class Ranking _______ of ______

7. Major/Concentration (including option if applicable): __________________________

8. Employment Experience (résumé may be attached): __________________________

9. Attach a personal essay describing interest in metallurgy/materials, career plans, long-range aspirations, special achievements and honors, employment experience, interdisciplinary skill/interest, and social values. (Maximum of two typewritten pages.)

10. Attach no more than two letters of recommendation from faculty or employer. One must be from a professor in applicant’s major department. (Use attached ‘Undergraduate Scholarship Recommendation Form’.)

11. Submit a current academic transcript through the Fall term (an official student copy is acceptable), and complete attached form listing titles of all currently enrolled courses.

12. Attach a photograph to be used for publication of award winners. Photograph will NOT be part of selection process.

PART 2: Need-Based Section: You must complete this section if you want to be considered for any of the need-based scholarships (which is most of them). Students at the junior or senior level studying in North America only are eligible. Need assessment will be based on this information.

A. Attach a brief personal statement regarding your financial need. How will this scholarship aid you in your academic goals?

B. Do you plan to apply for financial aid for the upcoming academic year? □ Yes □ No If No, why not? __________________________

C. Please provide for the next academic year: Annual Tuition Cost: $__________ Standard Room/Board Costs: $__________

D. Are you currently receiving financial aid? □ No □ Yes

E. Please complete the following information for the current academic year:

   Total Financial Aid Provided: Loans: $__________ Grants/Scholarships Awarded: $__________ Other: $__________

F. Please provide a Financial Aid contact to verify the above information:

   Name: ___________________________ Tel: ___________________________ Fax: ___________________________

Please sign below if this application is complete and accurate:

Signature: ___________________________ Date: ___________________________

MUST BE POSTMARKED BY 1 MAY.
Send completed application with attachments to:
ASM Materials Education Foundation Scholarship Program
Materials Park, OH 44073-0002
List titles of all currently enrolled courses (include course descriptions):

Course Listing

________________________________________________________________________
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________________________________________________________________________
Undergraduate Scholarship Recommendation Form

Name of Applicant: ________________________________

Name of Reference: ________________________________

Title/Address: _______________________________________

Telephone: ______________ Fax: ______________ E-mail: ______________

How long have you known the scholarship applicant? ________________________________

In what capacity are you familiar with the applicant’s education and/or personal background? ________________________________

EVALUATION:
In comparison with a representative group of undergraduate students who have had approximately the same amount of experience and training, how do you rate the applicant in:

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<th>Excellent (Upper 5%)</th>
<th>Above Average (Upper 10%)</th>
<th>Average (Upper 25%)</th>
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<tr>
<td>General academic ability</td>
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<td>Leadership potential</td>
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<td>Motivation and initiative</td>
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<td>Ability to work with others</td>
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<td>Imagination and creativity</td>
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<td>Potential to succeed in a materials science &amp; engineering program</td>
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COMMENTS (Do not attach additional letters.)
Please use the rest of this form to comment on any aspect of the applicant’s background, experiences, community involvement, etc., that you feel will help the Scholarship Selection Committee evaluate this individual.

________________________________________________________________________

________________________________________________________________________

________________________________________________________________________

________________________________________________________________________

Signature: ___________________________ Date: ___________________________

Please return this form to THE APPLICANT in a sealed envelope.

Scholarship deadline: __1 May__

Form may be photocopied.